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DATA SHEET

PART NO. : LD030A060H247P3-S64

REV : A / 0

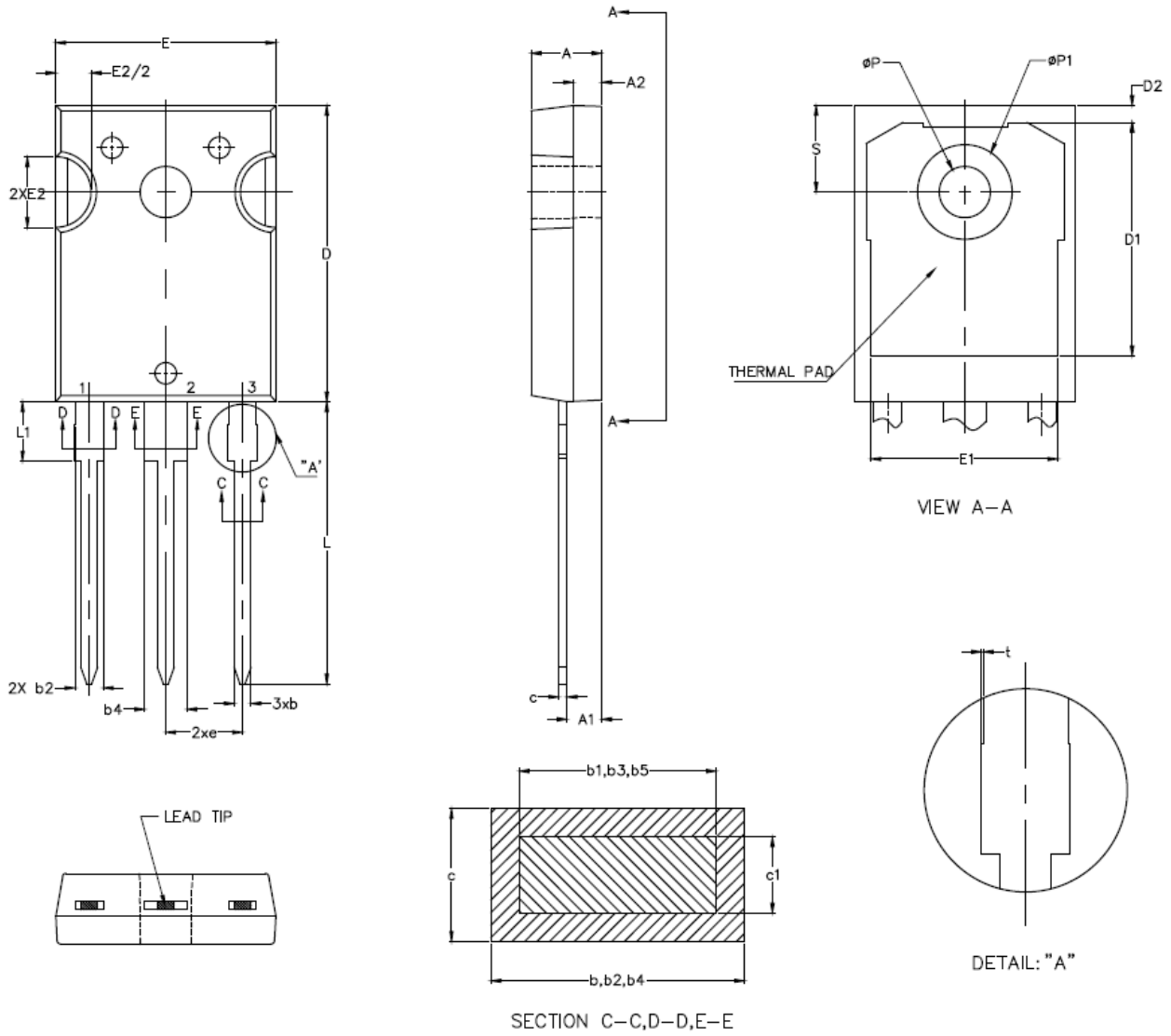
CUSTOMER'S APPROVAL : _____ DCC : _____

DRAWING NO. : DS-91P-22-0006

DATE : 2022-06-23

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Package Dimensions



Common dimensions(mm)							
Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	4.9	5.0	5.1	D1	16.25	16.55	16.85
A1	2.31	2.41	2.51	D2	1.05	1.17	1.35
A2	1.9	2.0	2.1	E	15.7	15.8	15.9
b	1.16	-	1.26	E1	13.2	-	-
b1	1.15	1.2	1.22	E2	4.9	5.0	5.1
b2	1.96	-	2.06	e	5.436BSC		
b3	1.95	2.0	2.02	L	19.8	19.92	20.1
b4	2.96	-	3.06	L1	-	-	4.3
b5	2.95	3.0	3.02	P	3.5	3.6	3.7
c	0.59	-	0.66	P1	-	-	7.4
c1	0.58	0.6	0.62	S	6.05	6.15	6.25
D	20.9	21.0	21.1	t	0.00	-	0.15



Trench Field-Stop Technology IGBT

LD030A060H247P3-S64

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Features

600V, 30A

$V_{CE(sat)(typ.)} = 1.90V @ V_{GE}=15V, I_C=30A$

High speed switching

Higher system efficiency

Soft current turn-off waveforms

Applications

Solar Converters

Uninterrupted Power Supply

Welding Converters

Mid to High Range Switching Frequency Converters

Key Performance and Package Parameters

V_{CE}	I_C	$V_{CEsat}, T_{vj}=25^{\circ}C$	T_{vjmax}
600V	30A	1.90V	175 $^{\circ}C$

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
V_{CES}	Collector-Emitter Voltage	600	V
V_{GES}	Gate-Emitter Voltage	± 30	V
I_C	Continuous Collector Current ($T_C=25^{\circ}C$)	80	A
	Continuous Collector Current ($T_C=100^{\circ}C$)	30	A
I_{CM}	Pulsed Collector Current (Note 1)	120	A
I_F	Diode Continuous Forward Current ($T_C=100^{\circ}C$)	30	A
I_{FM}	Diode Maximum Forward Current (Note 1)	120	A
t_{sc}	Short Circuit Withstand Time	10	us
P_D	Maximum Power Dissipation ($T_C=25^{\circ}C$)	300	W
	Maximum Power Dissipation ($T_C=100^{\circ}C$)	120	W
T_J	Operating Junction Temperature Range	-55 to +150	$^{\circ}C$
T_{STG}	Storage Temperature Range	-55 to +150	$^{\circ}C$

Thermal Data

Symbol	Parameter	Max.	Units
$R_{th j-c}$	Thermal Resistance, Junction to case for IGBT	0.42	$^{\circ}C/W$
$R_{th j-c}$	Thermal Resistance, Junction to case for Diode	1.5	$^{\circ}C/W$
$R_{th j-a}$	Thermal Resistance, Junction to Ambient	40	$^{\circ}C/W$

Electrical Characteristics (Tc=25°C unless otherwise noted.)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{CES}	Collector-Emitter Breakdown Voltage	$V_{GE}=0V, I_C=250\mu A$	600	-	-	V
I_{CES}	Collector-Emitter Leakage Current	$V_{CE}=600V, V_{GE}=0V$	-	-	100	μA
I_{GES}	Gate Leakage Current, Forward	$V_{GE}=30V, V_{CE}=0V$	-	-	100	nA
	Gate Leakage Current, Reverse	$V_{GE}=-30V, V_{CE}=0V$	-	-	-100	nA
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE}=V_{CE}, I_C=250\mu A$	4.5	-	6.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15V, I_C=30A$	-	1.9	2.3	V
Q_g	Total Gate Charge	$V_{CC}=480V$ $V_{GE}=15V$ $I_C=30A$	-	105		nC
Q_{ge}	Gate-Emitter Charge		-	33		nC
Q_{gc}	Gate-Collector Charge		-	72		nC
$t_{d(on)}$	Turn-on Delay Time		-	64	-	ns
t_r	Turn-on Rise Time	$V_{CC}=300V$ $V_{GE}=15V$ $I_C=30A$ $R_G=28\Omega$ Inductive Load $T_C=25^\circ C$	-	76	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	354	-	ns
t_f	Turn-off Fall Time		-	56	-	ns
E_{on}	Turn-on Switching Loss		-	0.9	-	mJ
E_{off}	Turn-off Switching Loss		-	0.85	-	mJ
E_{ts}	Total Switching Loss		-	1.75	-	mJ
C_{ies}	Input Capacitance	$V_{CE}=25V$	-	1395	-	pF
C_{oes}	Output Capacitance	$V_{GE}=0V$	-	68	-	pF
C_{res}	Reverse Transfer Capacitance	$f=100kHz$	-	26	-	pF

Diode Characteristics (TC=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_F	Diode Forward Voltage	$I_F=30A$	-	1.4	2.4	V
t_{rr}	Diode Reverse Recovery Time	$V_{CE}=300V$ $I_F=30A$ $dI_F/dt=200A/\mu s$	-	75		ns
I_{rr}	Diode peak Reverse Recovery Current		-	6		A
Q_{rr}	Diode Reverse Recovery Charge		-	220		nC

Note1: Repetitive rating, pulse width limited by maximum junction temperature

Typical Characteristics

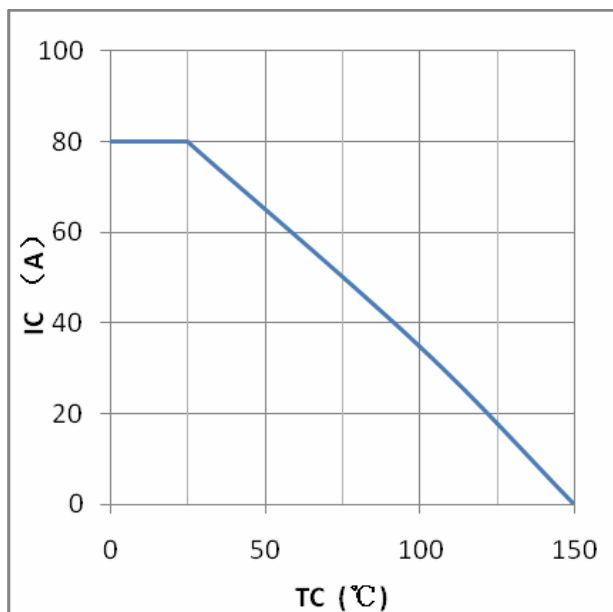


Figure1: maximum DC collector current VS. case temprature

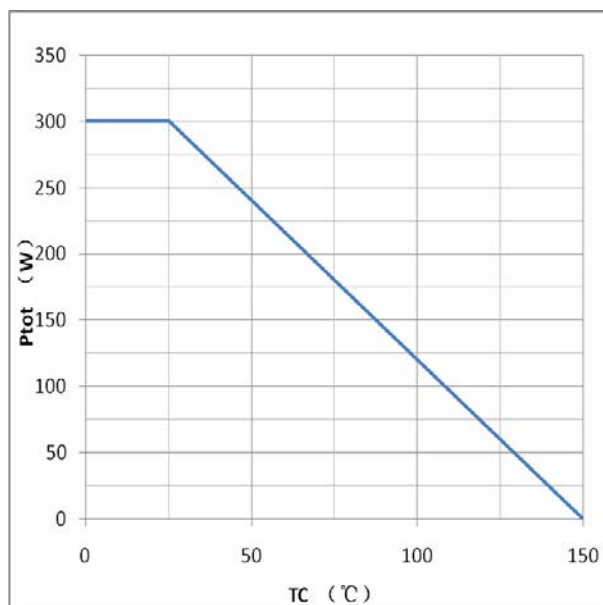


Figure2: power dissipation VS. case temprature

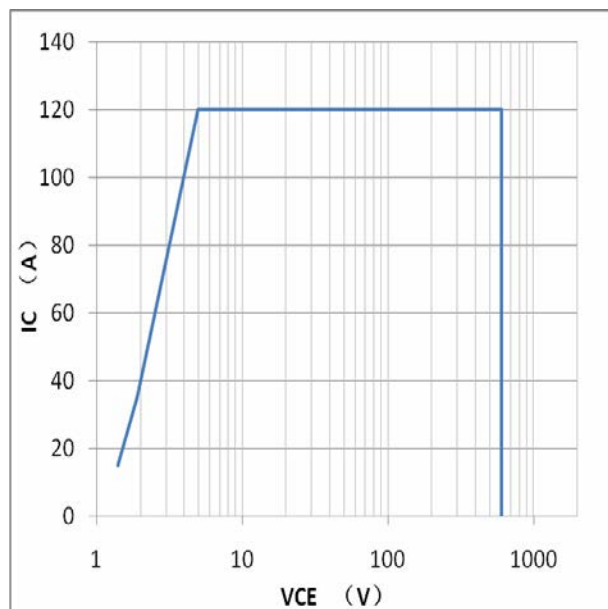


Figure3: reverse bias SOA, TJ=150°C, VGE=15V

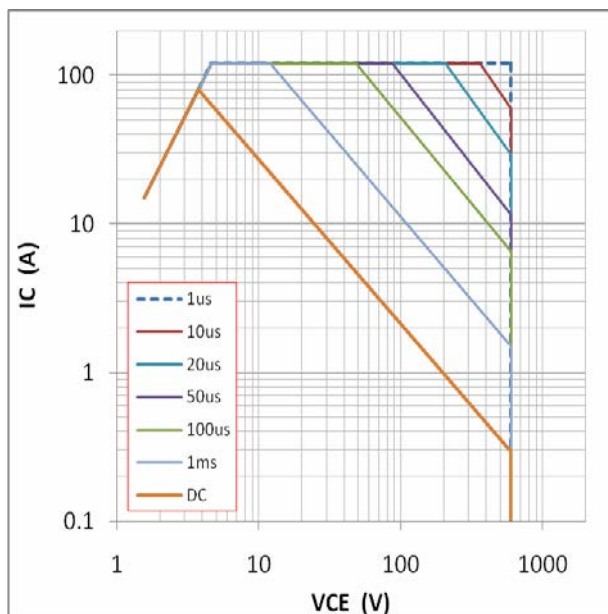


Figure4: forward SOA, TC=25°C, TJ≤150°C

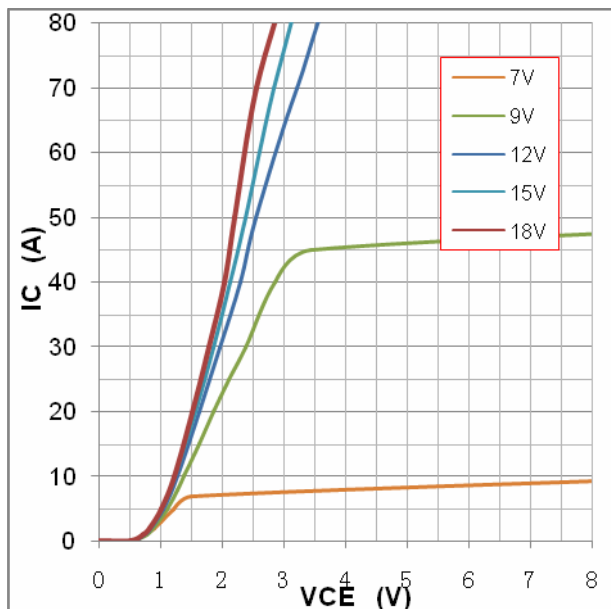


Figure5: typical IGBT output characteristics,
T_J=25°C; t_p=300us

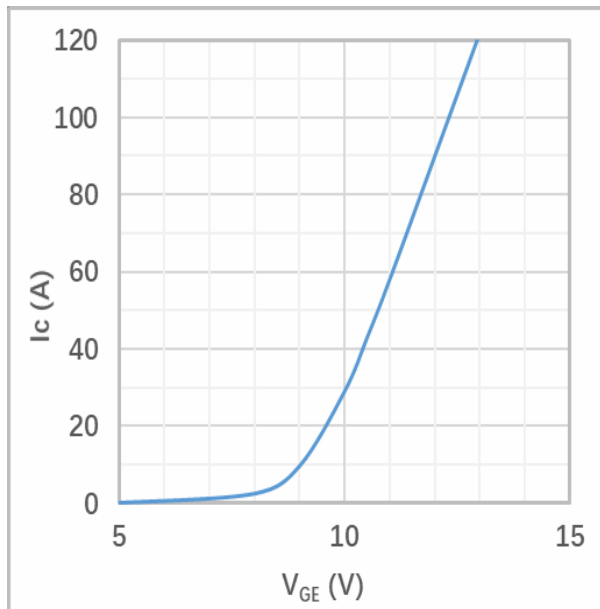


Figure6: typical trans characteristics, VCE=20V, t_p=20us

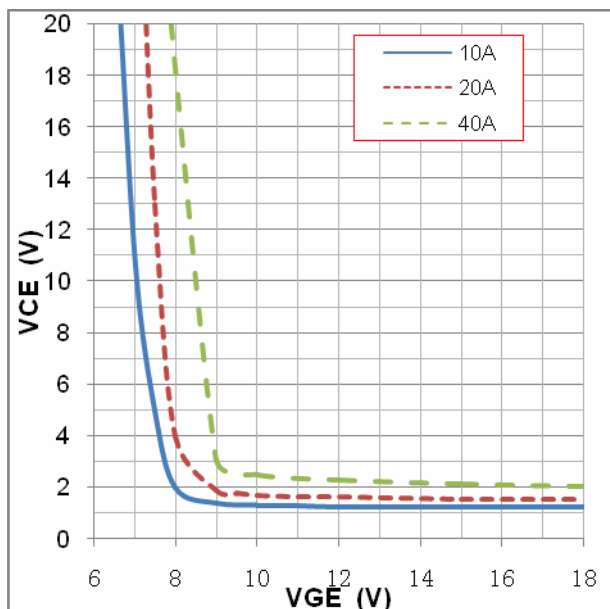


Figure7: typical VCE VS. VGE, T_J=25°C

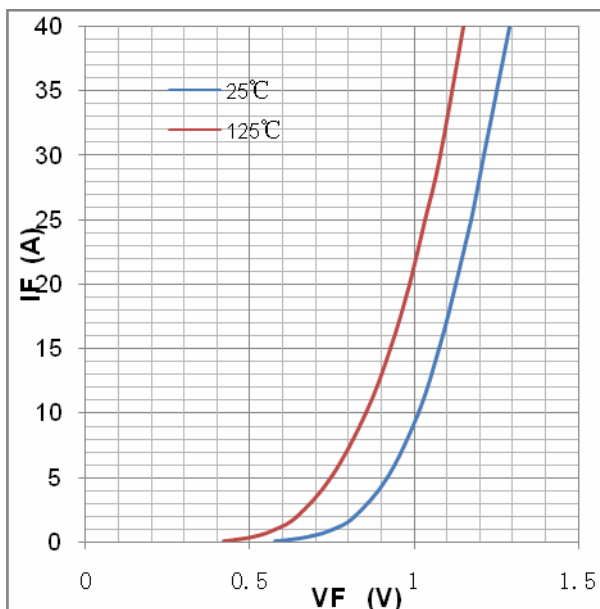


Figure8: typical diode forward characteristic, t_p=300us

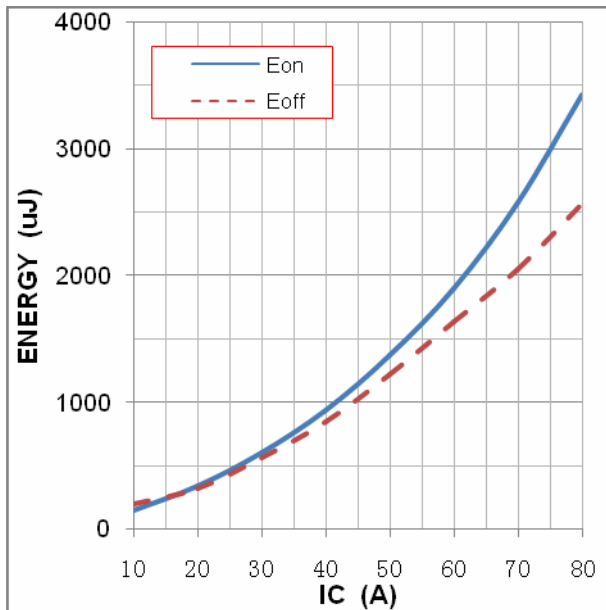


Figure9: typical energy loss VS. IC, TC=25°C,
L=500uH, VCE=300V, VGE=15V, Rg=28Ω

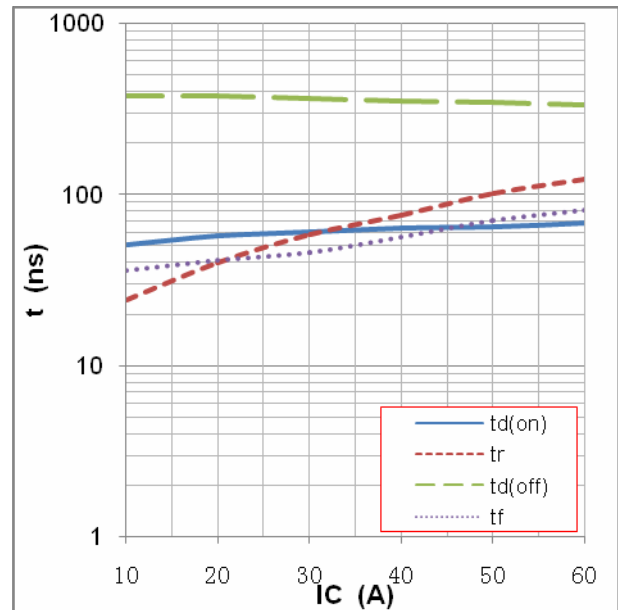


Figure10: typical switching time VS. IC, TC=25°C,
L=500uH, VCE=300V, VGE=15V, Rg=28Ω

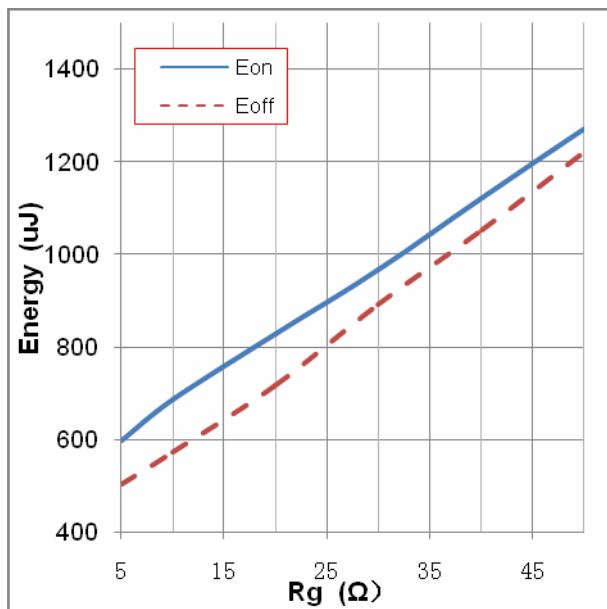


Figure11: typical energy loss VS. Rg, TC=25°C,
L=500uH, VCE=300V, VGE=15V, IC=30A

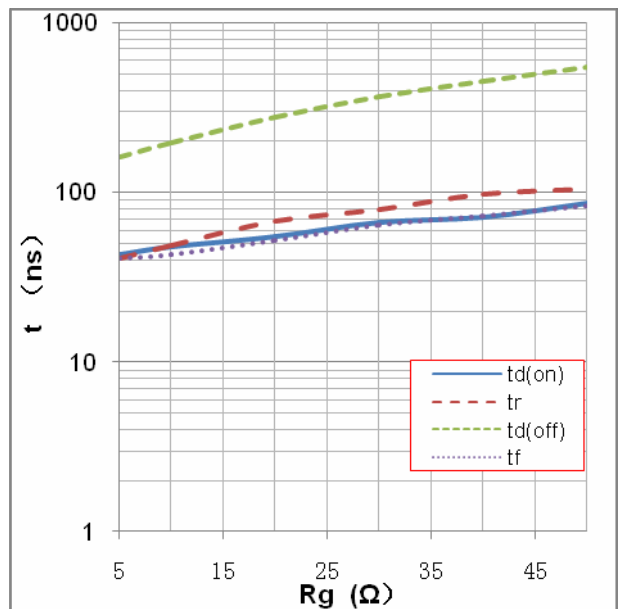


Figure12: typical switching time VS. Rg, TC=25°C,
L=500uH, VCE=300V, VGE=15V, IC=30A

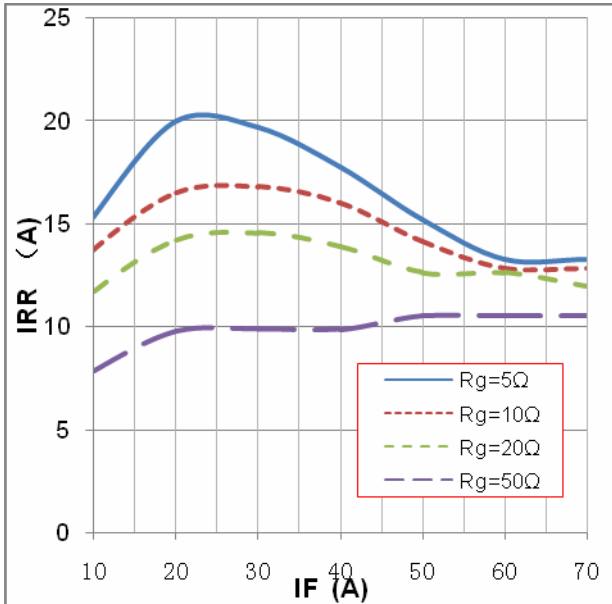


Figure13: typical diode IRR VS. IF, TC=25°C

VCC=300V, VGE=15V

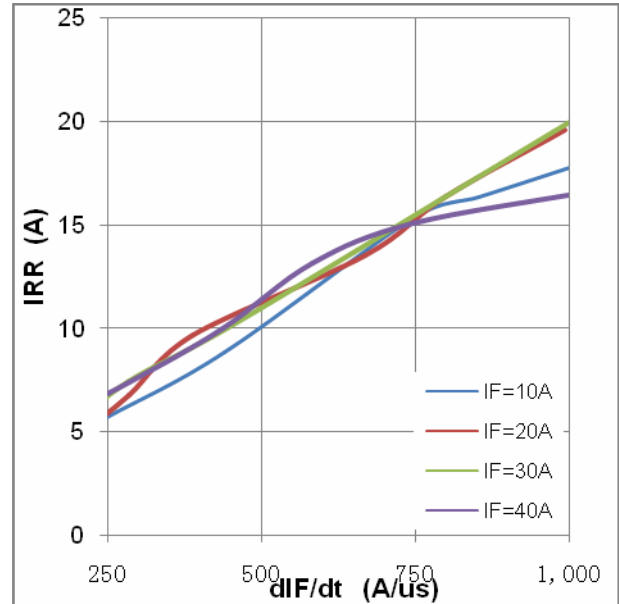


Figure14: typical diode IRR VS. dIF/dt

VCC=300V, VGE=15V

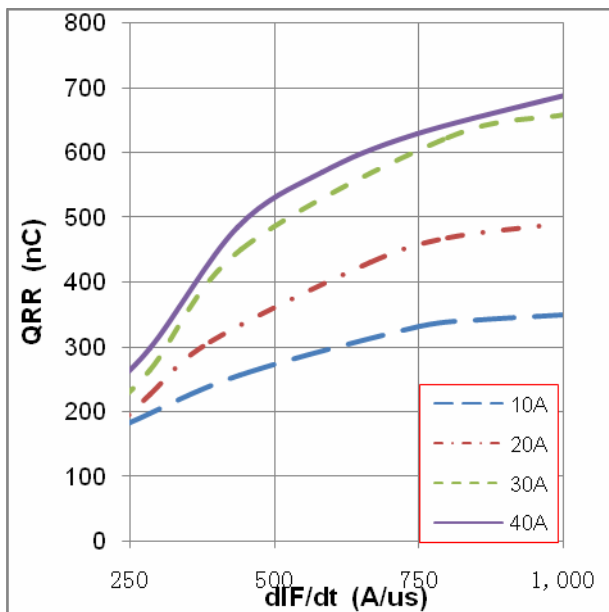


Figure15: typical diode QRR VS. dIF/dt

VCC=300V, VGE=15V

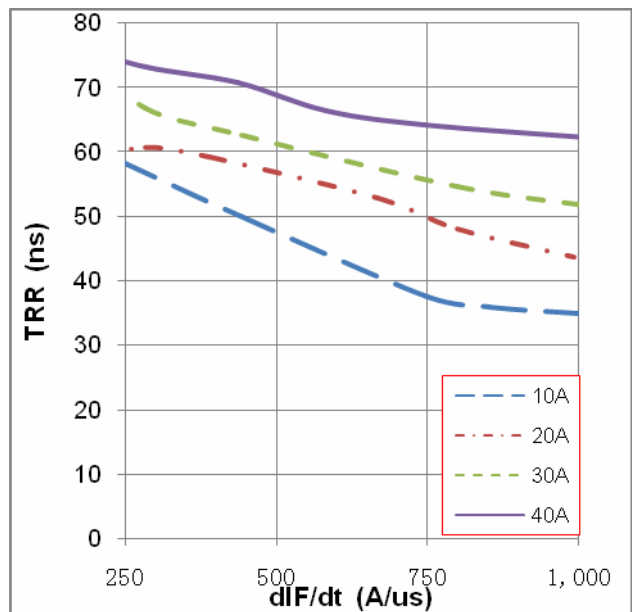


Figure16: typical diode TRR VS. dIF/dt,

VCC=300V, VGE=15V

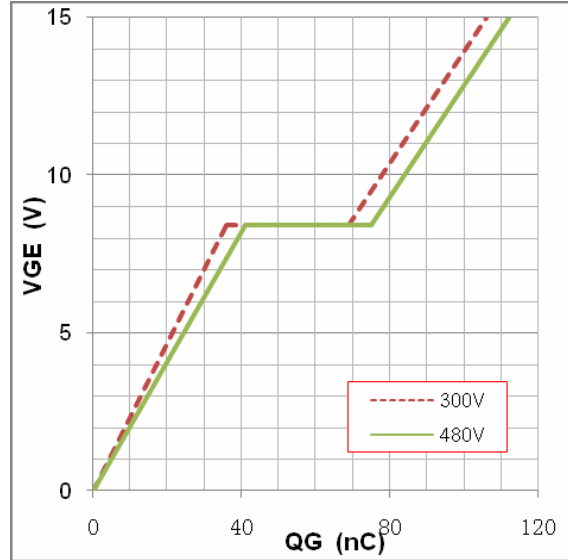
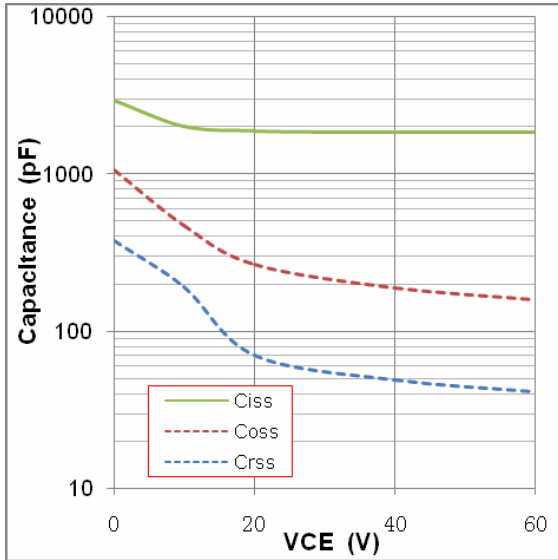


Figure17:typical capacitance VS. VCE,VGE=0V,f=100kHz Figure18:typical gate charge VS. VGE,IC=30

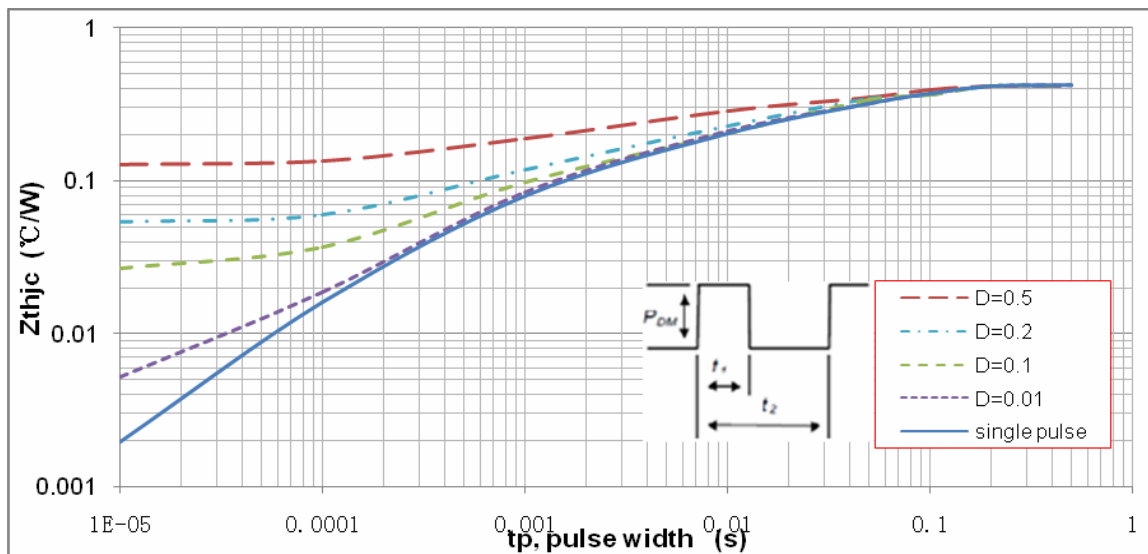


Figure19:normalised transient thermal impedance, junction-to-case

Note1.Duty factor $D=t_1/t_2$;Note2:peak $T_J=PDM \times Z_{thjc}+T_C$



Trench Field-Stop Technology IGBT

LD030A060H247P3-S64

REV:A / 0

● PART NO. SYSTEM :

L D 015A 120 H 247 P3 -XXX

